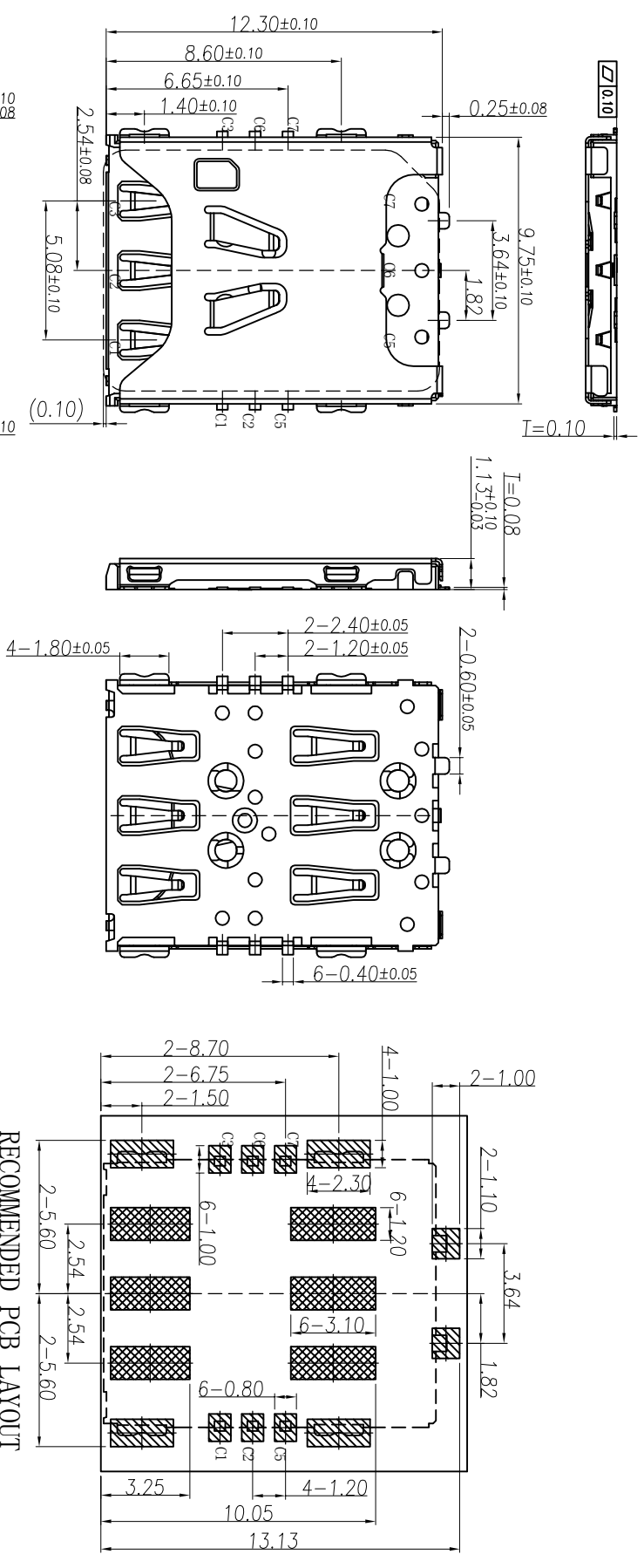


\* 所有原材料, 生产制程, 电镀必须符合IP要求



NOTES:  
1. MATERIAL:  
HOUSING: High Temperature Thermoplastic  
Terminal: Copper Alloy  
Shell: Stainless Steel

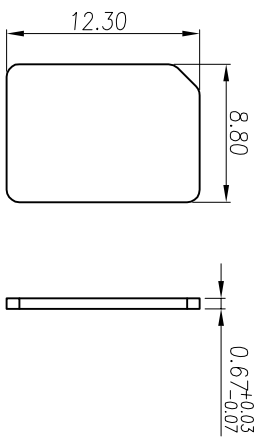
2. PLATING:  
Terminal: 50μ" Ni UNDERPLATED OVERALL  
G/F PLATED ON CONTACT AREA AND SOLDER AREA  
Shell: 50μ" Ni UNDERPLATED OVERALL

3. TECHNICAL SPECIALTY:  
RATED VOLTAGE: 30VACMAX.  
CURRENT RATING: 0.5AMAX.  
INSULATION RESISTANCE: 1000MΩ MIN  
CONTACT RESISTANCE: 100mΩ MAX  
WITHSTANDING VOLTAGE: 500VACFOR1MINUTES  
OPERATING TEMPERATURE: -40°C~+85°C Humidity: 80%RH MAX

RECOMMENDED PCB LAYOUT

TOLERANCE: ±0.05

- ▨ SMT SOLDER AREA
- ▨ COPPER RESTRICTED AREA
- 1. TOUCH AREA OF CONTACT
- TIPS NO ELECTRICAL FUNCTION
- 2. NO FIRST PCB LAYOUT
- CIRCUITS IN THE AREA



|              |      |         |            |
|--------------|------|---------|------------|
| REVISION NO. | X1   | EGR NO. | ---        |
| DESCRIPTION  | 新增规格 |         |            |
| MARK         | XXX  | DATE    | 2022.12.08 |

|                              |           |  |                  |
|------------------------------|-----------|--|------------------|
|                              |           | 深圳市鑫南天科技有限公司<br>Shen zhen Shi Xin Nan Tian Industrial Co., Ltd |                  |
| DIMENSIONS UNIT: mm          |           | DRAWING: CoCo  |                  |
| UNLESS OTHERWISE SPECIFIABLE |           | DATE: 2022.12.08   |                  |
| DIMENSION                    | TOLERANCE | CHECK: Ag  | DATE: 2022.12.08 |
| XX: ±                        | 0.35      | APPROVED: Jeff Lin   | DATE: 2022.12.08 |
| X.XX: ±                      | 0.20      | SCALE: 1:1   | REV.: X1         |
| X.XXX: ±                     | 0.10      | DWG ID: C D  | PAGE: 1 OF 2     |
| ANGULAR: ±                   | 1°        |  |                  |